

**FOR IMMEDIATE RELEASE****Rohm and Haas Electronic Materials Exhibits at IPC Expo,  
Introduces Broad Suite of Innovative Products for the Printed Circuit Market**

March 31- April 2, 2009, Mandalay Bay Resort & Convention Center, Las Vegas, Booth No. 807

**Marlborough, MA, March 23, 2009**– Rohm and Haas Electronic Materials (NYSE: ROH), exhibiting at this year's IPC show in Las Vegas, will present many new products that address the critical needs of the printed circuit market.

Rohm and Haas is introducing two innovative digital imaging processes for innerlayer and UV mask fabrication. The **LithoJet™ 210 Etch Resist** and **LithoJet™ UV Mask** inks, coupled with the latest inkjet technology from our equipment partners, can measurably help manufacturers improve yields, simplify process steps and reduce costs.

In response to customers' needs for more reliable, flexible and cost effective electroplating solutions, Rohm and Haas is introducing three acid copper plating products. **Copper Gleam™ CF 25** acid copper is designed for pattern, panel and button plate viafilling. **Copper Gleam™ CuPulse™ Plus** acid copper delivers the best performance in pulse plating technology. And **Copper Gleam™ HT-55** acid copper, our latest in high-performance DC electrolytic copper processes.

The company's next generation final finish process is catered to the ever evolving assembly and reliability requirements. The combination of **Duraposit™ SMT-88** electroless nickel and **Auroelectroless™ SMT-88** immersion gold provides a proven process with superior stability that is less prone to skip plating and nickel corrosion.

Several new Laminar™ dry film products for innerlayer photo resist (**Laminar™ E8000 series and E9012**), multi-functional Alkali etch (**Laminar™ E9200**), and laser direct imaging (**Laminar™ UD700**) will also be exhibited.

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**ABOUT Rohm and Haas Electronic Materials**

Rohm and Haas Electronic Materials develops and delivers innovative material solutions and processes to the electronic and optoelectronic industries. Focused on the interconnect and finishing, semiconductor manufacturing, advanced packaging, and flat panel display industries, its products and technologies are integral elements in electronic devices around the world.

With a broad range of core competencies in surface preparation, metallization, and imaging materials, Rohm and Haas Electronic Materials, Interconnect and Finishing Technologies, develops and delivers industry-leading processes and products for the printed circuit, electronic component, surface finishing, and solar energy industries.

**About Rohm and Haas Company**

Leading the way since 1909, Rohm and Haas Company (NYSE:ROH) is a global pioneer in the creation and development of innovative technologies and solutions for the specialty materials industry. The company's technologies are found in a wide range of markets including: Building and Construction, Electronics, Food and Retail, Household and Personal Care, Industrial Process, Packaging, Paper, Transportation and Water. Our innovative technologies and solutions help to improve life everyday, around the world. Based in Philadelphia, PA, the company generated annual sales of approximately \$9.6 billion in 2008. Visit [www.rohmhaas.com](http://www.rohmhaas.com) for more information. Imagine the possibilities™.

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